

POWER SCHOTTKY RECTIFIER
MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	7.5 A
V_{RRM}	45 V
T_j (max)	175 °C
V_F (max)	0.57 V

FEATURES AND BENEFITS

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Insulated package: ISOWATT220AC, TO-220FPAC
Insulating voltage = 2000V DC
Capacitance = 12pF

DESCRIPTION

Single Schottky rectifier suited for Switch Mode Power Supply and high frequency DC to DC converters.

Packaged either in TO-220AC, ISOWATT220AC, TO-220FPAC or D²PAK, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			45	V
$I_{F(RMS)}$	RMS forward current			20	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AC / D ² PAK	$T_c = 160^\circ\text{C}$	7.5	A
		ISOWATT220AC/ TO-220FPAC	$T_c = 145^\circ\text{C}$		
I_{FSM}	Surge non repetitive forward current	$t_p = 10 \text{ ms sinusoidal}$		150	A
I_{RRM}	Repetitive peak reverse current	$t_p = 2 \mu\text{s square } F = 1\text{kHz}$		1	A
I_{RSM}	Non repetitive peak reverse current	$t_p = 100 \mu\text{s square}$		2	A
T_{stg}	Storage temperature range	- 65 to + 175 °C			°C
T_j	Maximum operating junction temperature *	175 °C			°C
dV/dt	Critical rate of rise of reverse voltage	10000 V/μs			V/μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j - a)}$ thermal runaway condition for a diode on its own heatsink

STPS745D/F/G/FP

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th} (j-c)$	Junction to case	TO-220AC / D ² PAK	3.0	°C/W
		ISOWATT220AC/ TO-220FPAC	5.5	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			100	μA
		$T_j = 125^\circ\text{C}$			5	15	mA
V_F *	Forward voltage drop	$T_j = 125^\circ\text{C}$	$I_F = 7.5 \text{ A}$		0.5	0.57	V
		$T_j = 25^\circ\text{C}$	$I_F = 15 \text{ A}$			0.84	
		$T_j = 125^\circ\text{C}$	$I_F = 15 \text{ A}$		0.65	0.72	

Pulse test : * $t_p = 380 \mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation :

$$P = 0.42 \times I_{F(AV)} + 0.020 I_F^2(\text{RMS})$$

Fig. 1: Average forward power dissipation versus average forward current.

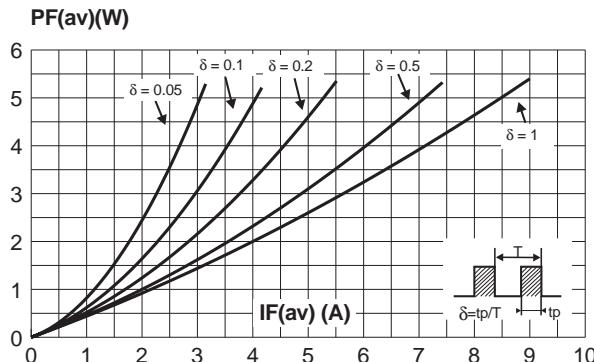


Fig. 3-1: Non repetitive surge peak forward current versus overload duration (maximum values) (TO-220AC and D²PAK).

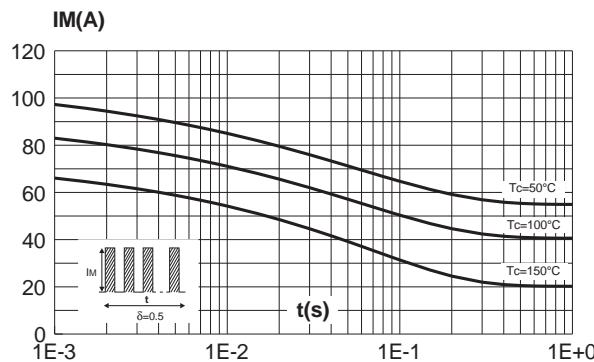


Fig. 4-1: Relative variation of thermal transient impedance junction to case versus pulse duration (TO-220AC and D²PAK).

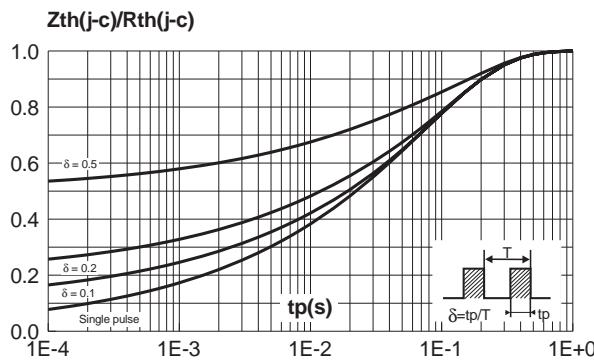


Fig. 2: Average current versus ambient temperature ($\delta = 0.5$).

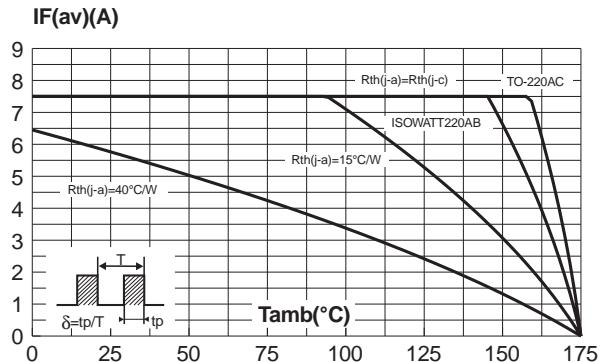


Fig. 3-2: Non repetitive surge peak forward current versus overload duration (maximum values) (ISOwatt220AC/TO-220FPAC).

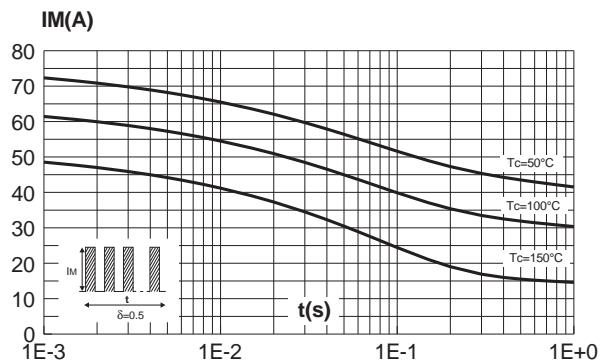
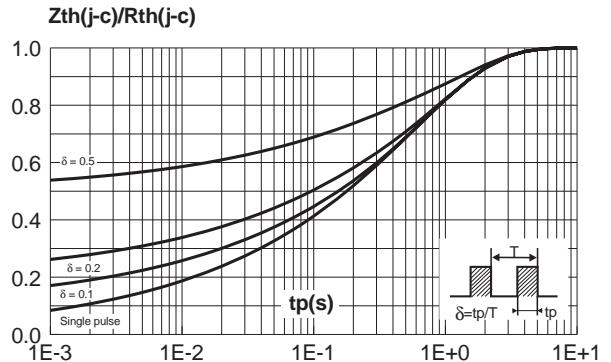


Fig. 4-2: Relative variation of thermal transient impedance junction to case versus pulse duration (ISOwatt220AC/TO-220FPAC).



STPS745D/F/G/FP

Fig. 5: Reverse leakage current versus reverse voltage applied (typical values).

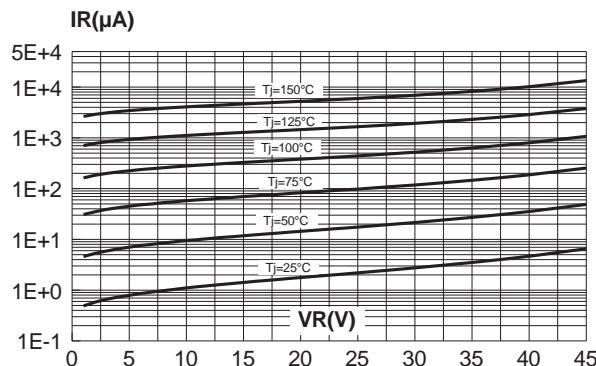


Fig. 6: Junction capacitance versus reverse voltage applied (typical values).

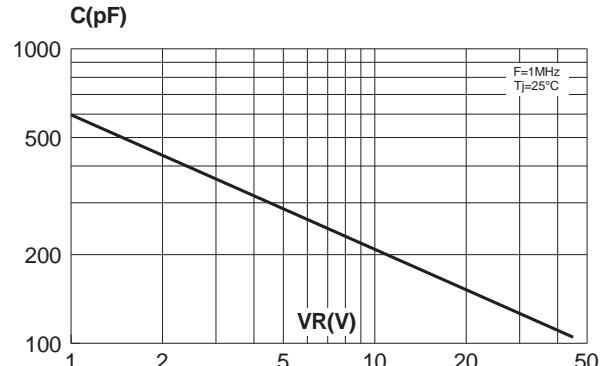


Fig. 7: Forward voltage drop versus forward current (maximum values).

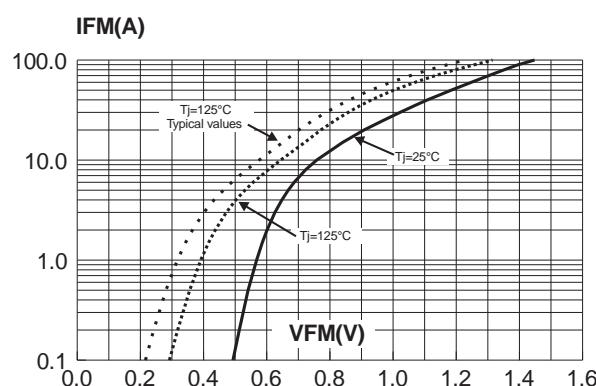
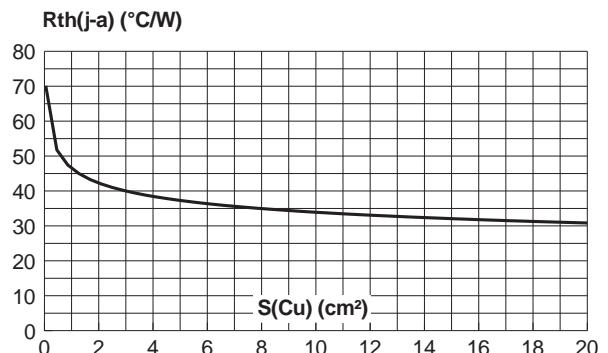


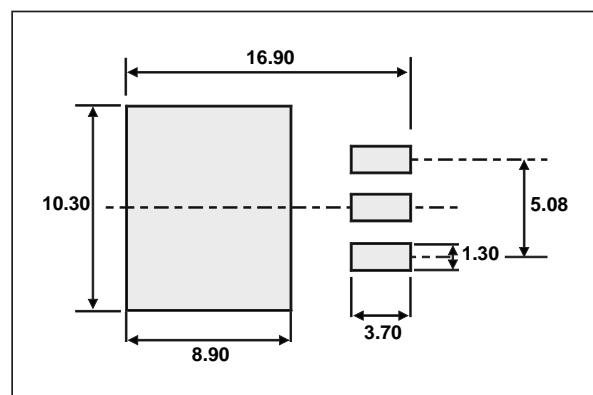
Fig. 8: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board, copper thickness: $35\mu m$).



PACKAGE MECHANICAL DATA
D²PAK (Plastic)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

FOOTPRINT DIMENSIONS (in millimeters)

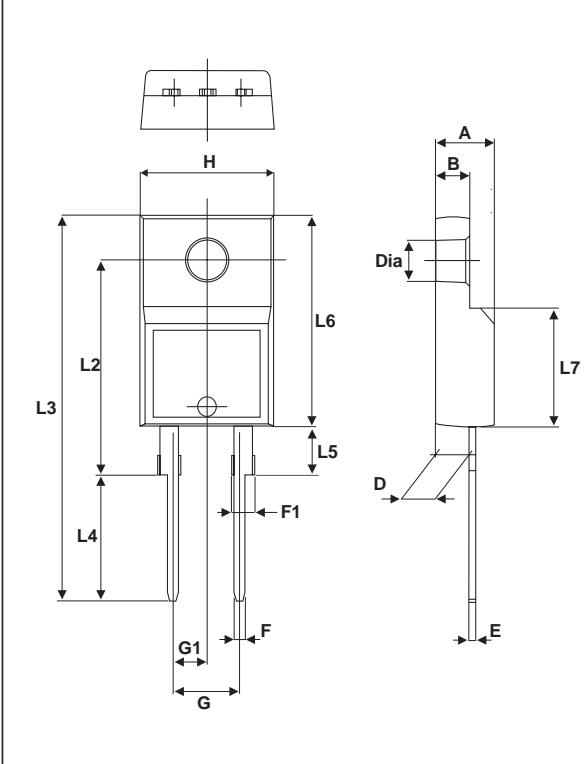


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PACKAGE MECHANICAL DATA TO-220AC

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

PACKAGE MECHANICAL DATA
TO-220FPAC



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

STPS745D/F/G/FP

PACKAGE MECHANICAL DATA ISOWATT220AC

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	2.50		2.70	0.098		0.106
D	2.40		2.75	0.094		0.108
E	0.40		0.70	0.016		0.028
F	0.75		1.00	0.030		0.039
F1	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
H	10.00		10.40	0.394		0.409
L2		16.00			0.630	
L3	28.60		30.60	1.125		1.205
L6	15.90		16.40	0.626		0.646
L7	9.00		9.30	0.354		0.366
Diam	3.00		3.20	0.118		0.126

Type	Marking	Package	Weight	Base qty	Delivery mode
STPS745D	STPS745D	TO-220AC	1.86 g.	50	Tube
STPS745F	STPS745F	ISOWATT220AC	2 g.	50	Tube
STPS745G	STPS745G	D ² PAK	1.48 g.	50	Tube
STPS745G-TR	STPS745G	D ² PAK	1.48 g.	1000	Tape & reel
STPS745FP	STPS745FP	TO-220FPAC	1.9 g.	50	Tube

- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N.m
- Maximum torque value: 0.7 N.m.
- Epoxy meets UL94,V0

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